

INCH-POUND

MIL-PRF-39015D
AMENDMENT 2
8 August 2002
SUPERSEDING
AMENDMENT 1
9 June 1998

PERFORMANCE SPECIFICATION
RESISTORS, VARIABLE, WIRE WOUND,
(LEAD SCREW ACTUATED),
NONESTABLISHED RELIABILITY, AND ESTABLISHED RELIABILITY,
GENERAL SPECIFICATION FOR

This amendment forms a part of MIL-PRF-39015D, dated 19 May 1997, and is approved for use by all Departments and Agencies of the Department of Defense.

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- * 2.2.1, STANDARDS, delete "MIL-STD-1276 - Leads for Electronic Component Parts".
- * 2.2.1, parenthesis note, delete "Defense Printing Service Detachment Office, Building 4D, Customer Service" and substitute "Document Automation and Production Service, Building 4D (DPM-DODSSP)".

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- * 3.5.3, second sentence, delete, and last sentence delete "suitably".

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- * 3.5.8, on third line between "process" and "has", add "(see appendix)".
- * 3.5.8.1 and 3.5.8.2, delete in its entirety.

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4.8.18c, delete in entirety.

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- * 4.8.25a, last sentence delete, and substitute "There shall be no circulation of air over the resistors other than that caused by heat of the resistors."

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- * 6.4.1, delete "(6.8.1)", and "(6.5.2)" and substitute "(6.7.1)" and "(6.4.2)", respectively.

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- * Section 2, delete and substitute:

"2. APPLICABLE DOCUMENTS

"2.1 General. The documents listed in this section are specified in sections 3, 4, and 5 of this specification. This section does not include documents cited in other sections of this specification or recommended for additional information or as examples. While every effort has been made to ensure the completeness of this list, document users are cautioned that they must meet all specified requirements documents cited in sections 3, 4, and 5 of this specification, whether or not they are listed.

"2.2.1 Specifications, standards, and handbooks. The following specifications, standards, and handbooks form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation (see 6.2).

"STANDARDS

"DEPARTMENT OF DEFENSE

"MIL-STD-1276 - Leads for Electronic Component Parts.

"(Unless otherwise indicated, copies of the above specifications, standards and handbooks are available from the Document Automation and Production Service, Building 4D (DPM-DODISS), 700 Robbins Avenue, Philadelphia PA 19111-5094.)

"2.3 Order of precedence. In the event of a conflict between the text of this document and the references cited herein (except for associated specifications, specification sheets, or MS sheets), the text of this document takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained."

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- * Add, section 5

"5. SOLDER DIP (RETIMMING) LEADS

"5.1 Solder dip (retinning) leads. The manufacturer (or his authorized category B or category C distributor) may solder dip/retin the leads of product supplied to this specification provided the solder dip process has been approved by the qualifying activity.

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“5.2 Qualifying activity approval. Approval of the solder dip process will be based on one of the following options:

- “a. When the original lead finish qualified was hot solder dip lead finish 52 of MIL-STD-1276 (NOTE: The 200 microinch maximum thickness is not applicable). The manufacturer shall use the same solder dip process for reflowing as used in the original manufacture of the product.
- “b. When the lead originally qualified was not hot solder dip lead finish 52 of MIL-STD-1276 as prescribed in 5.2a of this appendix, approval for the process to be used for solder dip shall be based on the following test procedure:
 - “(1) Thirty samples of any resistance value for each style and lead finish are subjected to the manufacturer's solder dip process. Following the solder dip process, the resistors are subjected to the dc resistance test (and other group A electricals). No defects are allowed.
 - “(2) Ten of the 30 samples are then subjected to the solderability test. No defects are allowed.
 - “(3) The remaining 20 samples are subjected to the resistance to solder heat test followed by the moisture resistance test.

“5.3 Solder dip/reflowing options: The manufacturer (or authorized category B or category C distributor) may solder dip/reflow as follows:

- “a. After the 100 percent group A screening tests: Unless otherwise approved (see 4.6.3.2.2) for lots subjected to this process, electrical measurements are required in accordance with group A, subgroup 2 (PPM.) (NOTE: The manufacturer may solder dip/reflow prior to the 100 percent electrical measurements of the group A, subgroup 1 tests). The percentage defective allowable (PDA) for the electrical measurements shall be as for the subgroup 1 tests.
- “b. As a corrective action, if the lot fails the group A solderability test: For lots subjected to this process, electrical measurements are required in accordance with group A, subgroup 2 (PPM). (NOTE: Results from this test shall not be used for PPM calculation).
- “c. After the group A inspection has been completed: Following the solder dip/reflowing process, the electrical measurements required in group A, subgroup 1, 100 percent screening test shall be repeated on 100 percent of the lot. The PDA for the electrical measurements shall be as for the subgroup 1 tests. Following these tests, the manufacturer shall submit the lot to the group A solderability test as specified in 4.8.12.”

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Custodians:

Army - CR
Navy - EC
Air Force - 11

Preparing activity:
Army - CR

(Project 5905-1665)

Review activities:

Army - AR, AT, AV, CR4, MI
Navy - AS, MC, OS
Air Force - 19, 99